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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inter Patent Application of:

Tai-Chong CHAI *et al.*

Serial No.: 09/497,421

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Group Art Unit: 2815

Examiner: L. Cruz

LEAD FRAME FOR AN INTEGRATED CIRCUIT CHIP (SMALL WINDOW)

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

**AMENDMENT AFTER FINAL REJECTION**

In response to the Office Action of January 22, 2002, please amend the claims as follows.

**IN THE CLAIMS**

1. (Three times Amended) A lead frame, for an integrated circuit chip having a frame engaging bottom surface for attachment to the frame by means of a chip attach material, said chip being formed with outer edges having defined dimensions, said frame comprising:

a unitary apertured frame having a central through aperture therein including a plurality of [unitary] uniform sidebars each having an upper chip-supporting surface for engaging the bottom of the surface of the chip with the chip attach material therebetween,

each of said sidebars having an inner [side] edge and an outer [side] edge, said inner [sides] edges defining [an] the central aperture,